300mm Fully-Automatic BG Tape Laminator

RAD-3520F/12

Outline
- High precision fully-automatic tape laminator.
- We have now improved the performance of the top-selling model “RAD-3510F/12” and have developed the “RAD-3520F/12,” which offers better performance and a smaller footprint.
- Performs non-contact alignment and tape lamination using a tape tension control function, as well as wafer handling and tape cutting using a multi-joint robot arm.
- Improves the wafer processing volume per roll of tape a maximum of 16%
  *When the tape is a 100m roll and the wafer size is 300mm (12 inch) in diameter
- FOUP opener with wafer mapping function is available as standard feature

Options
- Various cleaning functions
- Automatic cutter exchange function
- ESD (Electro-Static Discharge) countermeasures etc

External View

Facility

| Power Supply | Voltage     | AC200-230V ± 10% (AC190-253V) |
|             | Frequency   | 50/60Hz |
|             | Phase       | single phase |
|             | Power Consumption | 3.0kW |

Air supply
- Air Pressure: 0.6 ~ 0.8MPa
- Air Consumption: Less than 300L(ANR)

Applicable Wafer Size
- 200mm, 300mm
- Please inquire about options for compatibility with specific wafer sizes.

Size
- Width: 1,245 mm
- Depth: 1,850 mm
- Height: 1,920 mm
  *(Excluding the signal tower)*

Weight
- 1,250 kg

UPH
- 70 wafers/hour
- 100 wafers/hour (High-speed spec option)

The above processing capacity is based on following conditions
- Wafer: 300mm diameter non-polished mirror wafer
- Back grinding tape: Adwill P-4140A

Suitable Tapes
- Back grinding tape 「Adwill E series」,
  「Adwill P series」,